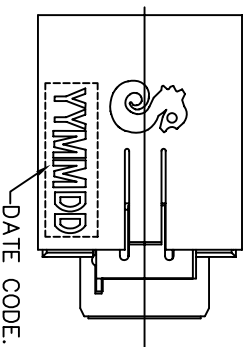
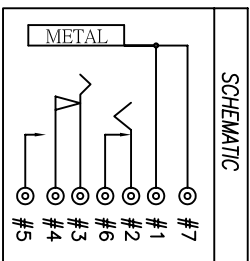
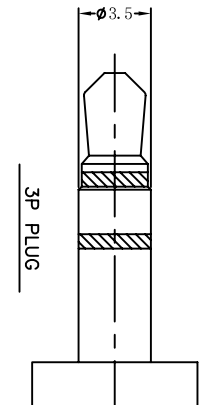


RECOMMENDED PCB LAYOUT (TOP VIEW)
(TOLERANCE: ±0.05)



- SPECIFICATIONS:
- INSULATION RESISTANCE BETWEEN ANY ADJACENT OPEN CIRCUIT TERMINAL SHELL NOT BE LESS THAN 100M Ω MEASURED BY 500 VDC MEGGER.
 - CONTACT RESISTANCE : 30mΩ MAX. (200mΩ MAX.METAL TO EARTH TO SHIELDING)
 - INSULATION VOLTAGE WITHSTAND :
500V AC FOR ONE MINUTE.
 - UNLESS OTHERWISE SPECIFIED. TEST IS TO BE MADE AT 5-35°C IN TEMPERATURE AND 45-85% IN HUMIDITY. BUT,IF ANY VAGUE DATA IS OCCURED ON TEST RESULT, ANOTHER TEST SHALL BE MADE AT 20°C±2°C IN TEMP., 60-70% IN HUMIDITY.
 - LIFE TEST : 5,000 CYCLES MIN. (NON-LOAD)
 - INSERTION FORCE : 0.4 - 3Kg.
 - WITHDRAWAL FORCE : 0.3 - 2Kg.
 - AFTER LIFE TEST, CONTACT RESISTANCE: 50mΩ MAX.
 - AFTER HUMIDITY TEST, INSULATION RESISTANCE: 50M Ω MIN.
 - MARKING: MARK "G.P." ON TOP OF CONNECTOR.
 - PACKING : TAPE & REEL.
 - TO CONFORM TO THE SINGATRON HSF SPECIFICATION"
 - GREEN PRODUCT IDENTIFICATION MARK ON JACK
 - GREEN PRODUCT IDENTIFICATION LABEL ON PACKING
 - FOR LEAD-FREE PROCESS.

G.P. PASS

NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
A	BODY+ METAL	1	BRASS	Ni 1.5 μm MIN.
B	EARTH	1	COPPER ALLOY 0.3t	LME COLOR(577C)
C	TIP SPRING	1	PHOSPHOR BRONZE 0.25t	
D	RING SPRING	1	PHOSPHOR BRONZE 0.2t	
E	SHUNT TERMINAL-A	1	BRASS 0.25t	
F	BREAK TERMINAL	1	PHOSPHOR BRONZE 0.2t	
G	TRANSFER TERMINAL	1	PHOSPHOR BRONZE 0.2t	
H	SHIELDING	1		Ni 1.5 μm MIN.

UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS:	ANGLES:
X :±0.5	X :±2°
X.X :±0.3	X.X :±1°
X.XX :±0.2	

TITLE	3.50 PHONE JACK
DWN	BRUCE 20080411
CHKD	Lussen 20080415
APVD	Max 20080418
PART NO.	2SJ-F351-S04
SCALE:	4:1
UNIT:	mm
SIZE:	A3
SHEET:	1 OF 1
REV:	A

CUSTOMER COPY(SZ)

REV/ECN NO OR DESCRIPTION	REVISED	DATE
A PDR:1080326-2A	BRUCE	2008.04.11